Build Up HDI (Standard)

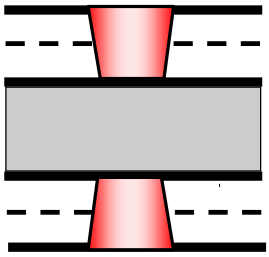
HDI04_1+2+1_1,15_35_engl

4 - Layers
Core: 0,93 mm Cu 35/35 µm

WE-Articel No.: | **1 + 2 + 1**

Customer:

WÜRTH ELEKTRONIK

layer description		configuration	Raw-Material	CU	PREPREG	Final Thickness	Customer requirements
Customer	WE					[µm]	[µm]
	TOP/VS		Foil	12 µm	1)	12	
					1 x 1080	60	
	2			35 µm		33	
			0,930 mm			930	
	3			35 µm		33	
					1 x 1080	60	
	BOT/RS		Foil	12 µm	1)	12	

1) copper thickness outer layers: appr. 55 µm

total material thickness:						1140	

Note: Lamination thickness for Prepregs depending on layout characteristics.

final lamination thickness:	**1,15**	+/-	0,09	mm			Date:	Engineer:
thickness with electro plated Cu:	1,24	+/-	0,12	mm				
total thickness with soldermask	1,30	+/-	0,14	mm				
customer requirement		+/-		mm	point:			

prepared: on	by	checked: on	by	approved: on	by	revision		
04.01.2006	**S. Keller**	04.05.2006	M.Kress	04.01.2006	R. Schönholz	00	page:	2+